LiPOLY®
SHIU LI TECHNOLOGY CO.,LTD

PK404

Thermal Conductive Gel Pad

LiPOLY PK404 is a material designed for gap filling. The thermal conductivity is 4.0 W/m*K. The hardness is Shore OO/30 with high flexibility, high compressibility, high insulating, great self-adhesive, which can cover the tolerance of design making it very stable. It also offers customized shape molding service.

FEATURES

/ Thermal conductivity: 4.0 W/m*K
/ Naturally tacky for ease of manufacture
/ Low thermal impedance
/ Available in a range of thicknesses

TYPICAL APPLICATION

/ Notebook computers
/ Heat pipe assemblies
/ Memory modules
/ TV hardware
/ Automotive electronics
/ Mobile devices
/ High speed mass storage drives
/ Set-top box
/ IP CAM

SPECIFICATIONS

/ Sheet form
/ Die-cut parts

TYPICAL PROPERTIES

PROPERTY	PK404	TEST METHOD	UNIT
Color	Blue	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	2.8	ASTM D792	g/cm³
Hardness	30	ASTM D2240	Shore OO
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	21	ASTM D5470 modify	%
Deflection @20 psi	27	ASTM D5470 modify	%
Deflection @30 psi	36	ASTM D5470 modify	%
Deflection @40 psi	41	ASTM D5470 modify	%
Deflection @50 psi	46	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Surface resistivity	>10¹⁰	ASTM D257	Ohm
Volume resistivity	>10¹⁰	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	4.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.502	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.452	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.423	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.380	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.361	ASTM D5470	°C-in²/ W

Thermal Resistance vs. Pressure vs. Deflection